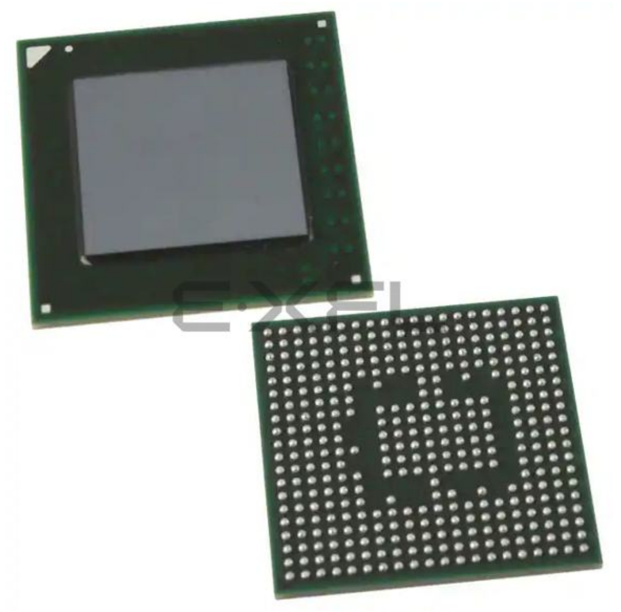
Intel - EP2AGX45CU17C5N Datasheet



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Details	
Product Status	Obsolete
Number of LABs/CLBs	1805
Number of Logic Elements/Cells	42959
Total RAM Bits	3517440
Number of I/O	156
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	358-LFBGA, FCBGA
Supplier Device Package	358-UBGA, FCBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx45cu17c5n

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Table 1–6. Recommended Operating Conditions for Arria II GZ Devices ***(Note 6)*** **(Part 2 of 2)**

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CCL_GXBLn} *(3)*	Transceiver clock power (left side)	—	1.05	1.1	1.15	V
V_{CCL_GXBRn} *(3)*	Transceiver clock power (right side)	—	1.05	1.1	1.15	V
V_{CCH_GXBLn} *(3)*	Transmitter output buffer power (left side)	—	1.33/1.425	1.4/1.5 *(5)*	1.575	V
V_{CCH_GXBRn} *(3)*	Transmitter output buffer power (right side)	—				
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	–40	—	100	°C
t_{RAMP}	Power supply ramp time	Normal POR (PORSEL=0)	0.05	—	100	ms
		Fast POR (PORSEL=1)	0.05	—	4	ms

Notes to Table 1–6:

(1) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.

(2) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.

(3) n = 0, 1, or 2.

(4) $V_{CCA\_L/R}$ must be connected to a 3.0-V supply if the clock multiplier unit (CMU) phase-locked loop (PLL), receiver clock data recovery (CDR), or both, are configured at a base data rate > 4.25 Gbps. For data rates up to 4.25 Gbps, you can connect $V_{CCA\_L/R}$ to either 3.0 V or 2.5 V.

(5) $V_{CCH\_GXBL/R}$ must be connected to a 1.4-V supply if the transmitter channel data rate is > 6.5 Gbps. For data rates up to 6.5 Gbps, you can connect $V_{CCH\_GXBL/R}$ to either 1.4 V or 1.5 V.

(6) Transceiver power supplies do not have power-on-reset (POR) circuitry. After initial power-up, violating the transceiver power supply operating conditions could lead to unpredictable link behavior.

DC Characteristics

This section lists the supply current, I/O pin leakage current, on-chip termination (OCT) accuracy and variation, input pin capacitance, internal weak pull-up and pull-down resistance, hot socketing, and Schmitt trigger input specifications.

Supply Current

Standby current is the current the device draws after the device is configured with no inputs or outputs toggling and no activity in the device. Because these currents vary largely with the resources used, use the Microsoft Excel-based Early Power Estimator (EPE) to get supply current estimates for your design.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter.

Table 1–11. OCT With and Without Calibration Specification for Arria II GX Device I/Os *(Note 1)* (Part 2 of 2)

Symbol	Description	Conditions (V)	Calibration Accuracy		Unit
			Commercial	Industrial	
50-Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	50-Ω series OCT with calibration	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	%
100-Ω R_D 2.5	100-Ω differential OCT without calibration	V_{CCIO} = 2.5	± 30	± 30	%

Note to Table 1–11:

(1) OCT with calibration accuracy is valid at the time of calibration only.

Table 1–12 lists the OCT termination calibration accuracy specifications for Arria II GZ devices.

Table 1–12. OCT with Calibration Accuracy Specifications for Arria II GZ Devices *(Note 1)*

Symbol	Description	Conditions (V)	Calibration Accuracy			Unit
			C2	C3,I3	C4,I4	
25-Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2 *(2)*	25-Ω series OCT with calibration	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50-Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2	50-Ω internal series OCT with calibration	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 8	± 8	± 8	%
50-Ω R_T 2.5, 1.8, 1.5, 1.2	50-Ω internal parallel OCT with calibration	V_{CCIO} = 2.5, 1.8, 1.5, 1.2	± 10	± 10	± 10	%
20-Ω, 40-Ω, and 60-Ω R_S 3.0, 2.5, 1.8, 1.5, 1.2 *(3)*	20-Ω, 40-Ω and 60-Ω R_S expanded range for internal series OCT with calibration	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	± 10	%
25-Ω $R_{S\_left\_shift}$ 3.0, 2.5, 1.8, 1.5, 1.2	25-Ω $R_{S\_left\_shift}$ internal left shift series OCT with calibration	V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2	± 10	± 10	± 10	%

Notes to Table 1–12:

(1) OCT calibration accuracy is valid at the time of calibration only.

(2) 25-Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.

(3) 20-Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.

Table 1–27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 2 of 2)

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-15 Class II	—	V_{REF} - 0.1	V_{REF} + 0.1	—	V_{REF} - 0.175	V_{REF} + 0.175	0.2 × V_{CCIO}	0.8 × V_{CCIO}	16	-16
HSTL-18 Class I	—	V_{REF} - 0.1	V_{REF} + 0.1	—	V_{REF} - 0.2	V_{REF} + 0.2	0.4	V_{CCIO} - 0.4	8	-8
HSTL-18 Class II	—	V_{REF} - 0.1	V_{REF} + 0.1	—	V_{REF} - 0.2	V_{REF} + 0.2	0.4	V_{CCIO} - 0.4	16	-16
HSTL-15 Class I	—	V_{REF} - 0.1	V_{REF} + 0.1	—	V_{REF} - 0.2	V_{REF} + 0.2	0.4	V_{CCIO} - 0.4	8	-8
HSTL-15 Class II	—	V_{REF} - 0.1	V_{REF} + 0.1	—	V_{REF} - 0.2	V_{REF} + 0.2	0.4	V_{CCIO} - 0.4	16	-16
HSTL-12 Class I	-0.15	V_{REF} - 0.08	V_{REF} + 0.08	V_{CCIO} + 0.15	V_{REF} - 0.15	V_{REF} + 0.15	0.25× V_{CCIO}	0.75× V_{CCIO}	8	-8
HSTL-12 Class II	-0.15	V_{REF} - 0.08	V_{REF} + 0.08	V_{CCIO} + 0.15	V_{REF} - 0.15	V_{REF} + 0.15	0.25× V_{CCIO}	0.75 × V_{CCIO}	16	-16

Table 1–28 lists the differential SSTL I/O standards for Arria II GX devices.

Table 1–28. Differential SSTL I/O Standards for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)		$V_{OX(AC)}$ (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.36	V_{CCIO}	V_{CCIO}/2 - 0.2	—	V_{CCIO}/2 + 0.2	0.7	V_{CCIO}	V_{CCIO}/2 - 0.15	—	V_{CCIO}/2 + 0.15
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V_{CCIO}	V_{CCIO}/2 - 0.175	—	V_{CCIO}/2 + 0.175	0.5	V_{CCIO}	V_{CCIO}/2 - 0.125	—	V_{CCIO}/2 + 0.125
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	—	V_{CCIO}/ 2	—	0.35	—	—	V_{CCIO}/ 2	—

Table 1–29 lists the differential SSTL I/O standards for Arria II GZ devices

Table 1–29. Differential SSTL I/O Standards for Arria II GZ Devices

I/O Standard	V_{CCIO} (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)		$V_{OX(AC)}$ (V)		
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max	Min	Typ	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	V_{CCIO} + 0.6	V_{CCIO}/2 - 0.2	—	V_{CCIO}/2 + 0.2	0.62	V_{CCIO} + 0.6	V_{CCIO}/2 - 0.15	—	V_{CCIO}/2 + 0.15
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	V_{CCIO} + 0.6	V_{CCIO}/2 - 0.175	—	V_{CCIO}/2 + 0.175	0.5	V_{CCIO} + 0.6	V_{CCIO}/2 - 0.125	—	V_{CCIO}/2 + 0.125
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	—	V_{CCIO}/ 2	—	0.35	—	—	V_{CCIO}/ 2	—

Switching Characteristics

This section provides performance characteristics of the Arria II GX and GZ core and periphery blocks for commercial grade devices. The following tables are considered final and are based on actual silicon characterization and testing. These numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions.

Transceiver Performance Specifications

Table 1–34 lists the Arria II GX transceiver specifications.

Table 1–34. Transceiver Specifications for Arria II GX Devices *(Note 1)* (Part 1 of 7)

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reference Clock														
Supported I/O Standards	1.2-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL													
Input frequency from `REFCLK` input pins	—	50	—	622.08	50	—	622.08	50	—	622.08	50	—	622.08	MHz
Input frequency from PLD input	—	50	—	200	50	—	200	50	—	200	50	—	200	MHz
Absolute V_{MAX} for a `REFCLK` pin	—	—	—	2.2	—	—	2.2	—	—	2.2	—	—	2.2	V
Absolute V_{MIN} for a `REFCLK` pin	—	–0.3	—	—	–0.3	—	—	–0.3	—	—	–0.3	—	—	V
Rise/fall time *(2)*	—	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.2	UI
Duty cycle	—	45	—	55	45	—	55	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	2000	200	—	2000	200	—	2000	200	—	2000	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	30	—	33	30	—	33	kHz

Table 1–34. Transceiver Specifications for Arria II GX Devices *(Note 1)* **(Part 2 of 7)**

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	—	100	—	—	100	—	Ω
V_{ICM} (AC coupled)	—	1100 ± 5%			1100 ± 5%			1100 ± 5%			1100 ± 5%			mV
V_{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise	10 Hz	—	—	-50	—	—	-50	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
	≥ 1 MHz	—	—	-130	—	—	-130	—	—	-130	—	—	-130	dBc/Hz
Transmitter REFCLK Phase Jitter (rms) for 100 MHz REFCLK *(3)*	10 KHz to 20 MHz	—	—	3	—	—	3	—	—	3	—	—	3	ps
R_{ref}	—	—	2000 ± 1%	—	—	2000 ± 1%	—	—	2000 ± 1%	—	—	2000 ± 1%	—	Ω
Transceiver Clocks														
Calibration block clock frequency (`cal_blk_clk`)	—	10	—	125	10	—	125	10	—	125	10	—	125	MHz

Table 1–34. Transceiver Specifications for Arria II GX Devices *(Note 1)* **(Part 3 of 7)**

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
`fixedclk` clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	—	125	—	—	125	—	MHz
`reconfig_clk` clock frequency	Dynamic reconfig. clock frequency	2.5/ 37.5 *(4)*	—	50	2.5/ 37.5 *(4)*	—	50	2.5/ 37.5 *(4)*	—	50	2.5/ 37.5 *(4)*	—	50	MHz
Delta time between `reconfig_clks` *(5)*	—	—	—	2	—	—	2	—	—	2	—	—	2	ms
Transceiver block minimum power-down pulse width	—	—	1	—	—	1	—	—	1	—	—	1	—	µs
Receiver														
Supported I/O Standards	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, 2.5-V PCML, LVPECL, and LVDS													
Data rate *(13)*	—	600	—	6375	600	—	3750	600	—	3750	600	—	3125	Mbps
Absolute V_{MAX} for a receiver pin *(6)*	—	—	—	1.5	—	—	1.5	—	—	1.5	—	—	1.5	V
Absolute V_{MIN} for a receiver pin	—	-0.4	—	—	-0.4	—	—	-0.4	—	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p)	V_{ICM} = 0.82 V setting	—	—	2.7	—	—	2.7	—	—	2.7	—	—	2.7	V
	V_{ICM} =1.1 V setting *(7)*	—	—	1.6	—	—	1.6	—	—	1.6	—	—	1.6	V

Table 1–34. Transceiver Specifications for Arria II GX Devices *(Note 1)* **(Part 4 of 7)**

Symbol/ Description	Condition	I3			C4			C5 and I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Minimum peak-to-peak differential input voltage V_{ID} (diff p-p)	—	100	—	—	100	—	—	100	—	—	100	—	—	mV
V_{ICM}	V_{ICM} = 0.82 V setting	—	820	—	—	820	—	—	820	—	—	820	—	mV
	V_{ICM} =1.1 V setting *(7)*	—	1100	—	—	1100	—	—	1100	—	—	1100	—	mV
Differential on-chip termination resistors	100–Ω setting	—	100	—	—	100	—	—	100	—	—	100	—	Ω
Return loss differential mode	PCIe				50 MHz to 1.25 GHz: –10dB									
	XAUI				100 MHz to 2.5 GHz: –10dB									
Return loss common mode	PCIe				50 MHz to 1.25 GHz: –6dB									
	XAUI				100 MHz to 2.5 GHz: –6dB									
Programmable PPM detector *(8)*	—	± 62.5, 100, 125, 200, 250, 300, 500, 1000												ppm
Run length	—	—	80	—	—	80	—	—	80	—	—	80	—	UI
Programmable equalization	—	—	—	7	—	—	7	—	—	7	—	—	7	dB
Signal detect/loss threshold	PCIe Mode	65	—	175	65	—	175	65	—	175	65	—	175	mV
CDR LTR time *(9)*	—	—	—	75	—	—	75	—	—	75	—	—	75	µs
CDR minimum T1b *(10)*	—	15	—	—	15	—		15	—	—	15	—	—	µs

Table 1–35 lists the transceiver specifications for Arria II GZ devices.

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 1 of 5)

Symbol/ Description	Conditions	–C3 and –I3 *(1)*			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Reference Clock								
Supported I/O Standards	1.2-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL							
Input frequency from `REFCLK` input pins	—	50	—	697	50	—	637.5	MHz
Phase frequency detector (CMU PLL and receiver CDR)	—	50	—	325	50	—	325	MHz
Absolute V_{MAX} for a `REFCLK` pin	—	—	—	1.6	—	—	1.6	V
Operational V_{MAX} for a `REFCLK` pin	—	—	—	1.5	—	—	1.5	V
Absolute V_{MIN} for a `REFCLK` pin	—	-0.4	—	—	-0.4	—	—	V
Rise/fall time *(2)*	—	—	—	0.2	—	—	0.2	UI
Duty cycle	—	45	—	55	45	—	55	%
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	mV
Spread-spectrum modulating clock frequency	PCIe	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to -0.5%	—	—	0 to -0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	Ω
V_{ICM} (AC coupled)	—	1100 ± 10%			1100 ± 10%			mV
V_{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise	10 Hz	—	—	-50	—	—	-50	dBc/Hz
	100 Hz	—	—	-80	—	—	-80	dBc/Hz
	1 KHz	—	—	-110	—	—	-110	dBc/Hz
	10 KHz	—	—	-120	—	—	-120	dBc/Hz
	100 KHz	—	—	-120	—	—	-120	dBc/Hz
	≥ 1 MHz	—	—	-130	—	—	-130	dBc/Hz
Transmitter REFCLK Phase Jitter (rms) for 100 MHz REFCLK *(3)*	10 KHz to 20 MHz	—	—	3	—	—	3	ps
R_{REF}	—	—	2000 ± 1%	—	—	2000 ± 1%	—	Ω

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 5 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
-3 dB Bandwidth	PCIe Gen1	2.5 - 3.5						MHz
	PCIe Gen2	6 - 8						MHz
	(OIF) CEI PHY at 4.976 Gbps	7 - 11						MHz
	(OIF) CEI PHY at 6.375 Gbps	5 - 10						MHz
	XAUI	2 - 4						MHz
	SRIO 1.25 Gbps	3 - 5.5						MHz
	SRIO 2.5 Gbps	3 - 5.5						MHz
	SRIO 3.125 Gbps	2 - 4						MHz
	GIGE	2.5 - 4.5						MHz
	SONET OC12	1.5 - 2.5						MHz
	SONET OC48	3.5 - 6						MHz
Transceiver-FPGA Fabric Interface								
Interface speed	—	25	—	325	25	—	250	MHz
Digital reset pulse width	—	Minimum is two parallel clock cycles						—

Notes to Table 1–35:

(1) The 3x speed grade is the fastest speed grade offered in the following Arria II GZ devices: EP2AGZ225, EP2AGZ300, and EP2AGZ350.

(2) The rise and fall time transition is specified from 20% to 80%.

(3) To calculate the REFCLK rms phase jitter requirement at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f (MHz) = REFCLK rms phase jitter at 100 MHz * 100/f.

(4) The minimum `reconfig_clk` frequency is 2.5 MHz if the transceiver channel is configured in **Transmitter only** mode. The minimum `reconfig_clk` frequency is 37.5 MHz if the transceiver channel is configured in **Receiver only** or **Receiver and Transmitter** mode.

(5) If your design uses more than one dynamic reconfiguration controller (`altgx_reconfig`) instances to control the transceiver (`altgx`) channels physically located on the same side of the device AND if you use different `reconfig_clk` sources for these `altgx_reconfig` instances, the delta time between any two of these `reconfig_clk` sources becoming stable must not exceed the maximum specification listed.

(6) The device cannot tolerate prolonged operation at this absolute maximum.

(7) You must use the 1.1-V RX V_{ICM} setting if the input serial data standard is LVDS.

(8) The differential eye opening specification at the receiver input pins assumes that Receiver Equalization is disabled. If you enable Receiver Equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level. Use H-Spice simulation to derive the minimum eye opening requirement with Receiver Equalization enabled.

(9) The rate matcher supports only up to ± 300 ppm.

(10) Time taken to `rx_pll_locked` goes high from `rx_analogreset` de-assertion. Refer to Figure 1–1 on page 1–33.

(11) Time for which the CDR must be kept in lock-to-reference mode after `rx_pll_locked` goes high and before `rx_locktodata` is asserted in manual mode. Refer to Figure 1–1 on page 1–33.

(12) Time taken to recover valid data after the `rx_locktodata` signal is asserted in manual mode. Refer to Figure 1–1 on page 1–33.

(13) Time taken to recover valid data after the `rx_freqlocked` signal goes high in automatic mode. Refer to Figure 1–2 on page 1–33.

(14) A GPLL may be required to meet the PMA-FPGA fabric interface timing above certain data rates. For more information, refer to the *Transceiver Clocking for Arria II Devices* chapter.

(15) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.

(16) To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Figure 1–3 shows the differential receiver input waveform.

Figure 1–3. Receiver Input Waveform

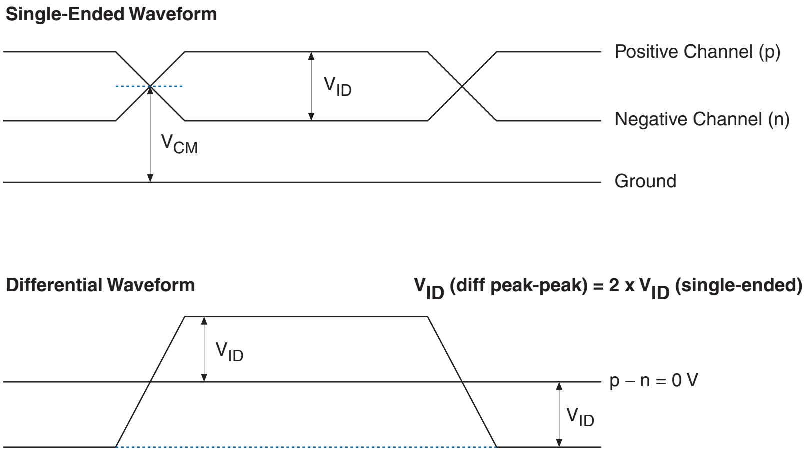


Figure 1–4 shows the transmitter output waveform.

Figure 1–4. Transmitter Output Waveform

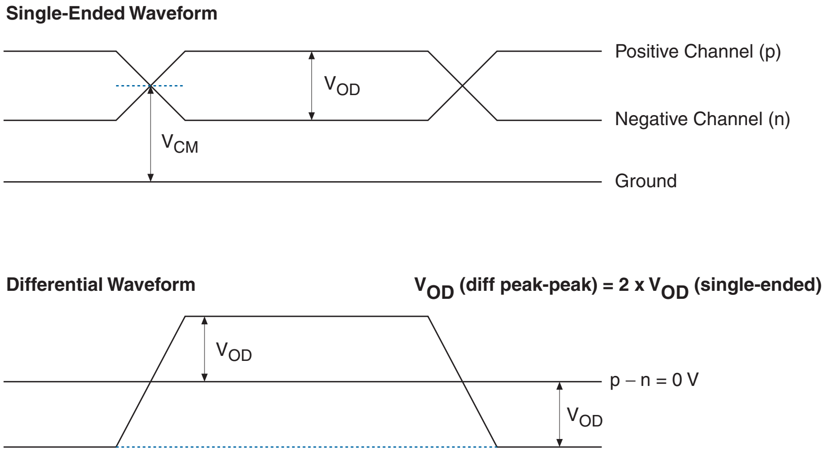


Table 1–36 lists the typical V_{OD} for TX term that equals 85 Ω for Arria II GZ devices.

Table 1–36. Typical V_{OD} Setting, TX Term = 85 Ω for Arria II GZ Devices

Symbol	V_{OD} Setting (mV)							
	0	1	2	3	4	5	6	7
V_{OD} differential peak-to-peak Typical (mV)	170 ± 20%	340 ± 20%	510 ± 20%	595 ± 20%	680 ± 20%	765 ± 20%	850 ± 20%	1020± 20%

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices *(Note 1)* **(Part 2 of 10)**

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Jitter tolerance at 2488.32 Mbps	Jitter frequency = 0.06 KHz Pattern = PRBS15	> 15			> 15			> 15			> 15			UI
	Jitter frequency = 100 KHZ Pattern = PRBS15	> 1.5			> 1.5			> 1.5			> 1.5			UI
	Jitter frequency = 1 MHz Pattern = PRBS15	> 0.15			> 0.15			> 0.15			> 0.15			UI
	Jitter frequency = 10 MHz Pattern = PRBS15	> 0.15			> 0.15			> 0.15			> 0.15			UI
XAUI Transmit Jitter Generation *(3)*														
Total jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.3	—	—	0.3	—	—	0.3	—	—	0.3	UI
Deterministic jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
XAUI Receiver Jitter Tolerance *(3)*														
Total jitter	—	> 0.65			> 0.65			> 0.65			> 0.65			UI
Deterministic jitter	—	> 0.37			> 0.37			> 0.37			> 0.37			UI
Peak-to-peak jitter	Jitter frequency = 22.1 KHz	> 8.5			> 8.5			> 8.5			> 8.5			UI
Peak-to-peak jitter	Jitter frequency = 1.875 MHz	> 0.1			> 0.1			> 0.1			> 0.1			UI
Peak-to-peak jitter	Jitter frequency = 20 MHz	> 0.1			> 0.1			> 0.1			> 0.1			UI
PCIe Transmit Jitter Generation *(4)*														
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	—	—	0.25	—	—	0.25	—	—	0.25	—	—	0.25	UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices *(Note 1)*, *(2)* **(Part 2 of 7)**

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Jitter tolerance at 2488.32 Mbps	Jitter frequency = 0.06 KHz Pattern = PRBS15	> 15			> 15			UI
	Jitter frequency = 100 KHZ Pattern = PRBS15	> 1.5			> 1.5			UI
	Jitter frequency = 1 MHz Pattern = PRBS15	> 0.15			> 0.15			UI
	Jitter frequency = 10 MHz Pattern = PRBS15	> 0.15			> 0.15			UI
Fibre Channel Transmit Jitter Generation *(4)*, *(5)*								
Total jitter FC-1	Pattern = CRPAT	—	—	0.23	—	—	0.23	UI
Deterministic jitter FC-1	Pattern = CRPAT	—	—	0.11	—	—	0.11	UI
Total jitter FC-2	Pattern = CRPAT	—	—	0.33	—	—	0.33	UI
Deterministic jitter FC-2	Pattern = CRPAT	—	—	0.2	—	—	0.2	UI
Total jitter FC-4	Pattern = CRPAT	—	—	0.52	—	—	0.52	UI
Deterministic jitter FC-4	Pattern = CRPAT	—	—	0.33	—	—	0.33	UI
Fibre Channel Receiver Jitter Tolerance *(4)*, *(6)*								
Deterministic jitter FC-1	Pattern = CJTPAT	> 0.37			> 0.37			UI
Random jitter FC-1	Pattern = CJTPAT	> 0.31			> 0.31			UI
Sinusoidal jitter FC-1	Fc/25000	> 1.5			> 1.5			UI
	Fc/1667	> 0.1			> 0.1			UI
Deterministic jitter FC-2	Pattern = CJTPAT	> 0.33			> 0.33			UI
Random jitter FC-2	Pattern = CJTPAT	> 0.29			> 0.29			UI
Sinusoidal jitter FC-2	Fc/25000	> 1.5			> 1.5			UI
	Fc/1667	> 0.1			> 0.1			UI
Deterministic jitter FC-4	Pattern = CJTPAT	> 0.33			> 0.33			UI
Random jitter FC-4	Pattern = CJTPAT	> 0.29			> 0.29			UI
Sinusoidal jitter FC-4	Fc/25000	> 1.5			> 1.5			UI
	Fc/1667	> 0.1			> 0.1			UI
XAUI Transmit Jitter Generation *(7)*								
Total jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.3	—	—	0.3	UI
Deterministic jitter at 3.125 Gbps	Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
XAUI Receiver Jitter Tolerance *(7)*								
Total jitter	—	> 0.65			> 0.65			UI
Deterministic jitter	—	> 0.37			> 0.37			UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices *(Note 1)*, *(2)* (Part 3 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Peak-to-peak jitter	Jitter frequency = 22.1 KHz	> 8.5			> 8.5			UI
Peak-to-peak jitter	Jitter frequency = 1.875 MHz	> 0.1			> 0.1			UI
Peak-to-peak jitter	Jitter frequency = 20 MHz	> 0.1			> 0.1			UI
PCIe Transmit Jitter Generation *(8)*								
Total jitter at 2.5 Gbps (Gen1)—x1, x4, and x8	Compliance pattern	—	—	0.25	—	—	0.25	UI
Total jitter at 5 Gbps (Gen2)—x1, x4, and x8	Compliance pattern	—	—	0.25	—	—	—	UI
PCIe Receiver Jitter Tolerance *(8)*								
Total jitter at 2.5 Gbps (Gen1)	Compliance pattern	> 0.6			> 0.6			UI
Total jitter at 5 Gbps (Gen2)	Compliance pattern	Not supported			Not supported			UI
PCIe (Gen 1) Electrical Idle Detect Threshold								
$V_{RX\text{-}IDLE\text{-}DETDIFFp\text{-}p}$ *(9)*	Compliance pattern	65	—	175	65	—	175	UI
SRIO Transmit Jitter Generation *(10)*								
Deterministic jitter (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.17	—	—	0.17	UI
Total jitter (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
SRIO Receiver Jitter Tolerance *(10)*								
Deterministic jitter tolerance (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.37			> 0.37			UI
Combined deterministic and random jitter tolerance (peak-to-peak)	Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.55			> 0.55			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 22.1 KHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 8.5			> 8.5			UI
	Jitter frequency = 1.875 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			UI
	Jitter frequency = 20 MHz Data rate = 1.25, 2.5, 3.125 Gbps Pattern = CJPAT	> 0.1			> 0.1			UI
GIGE Transmit Jitter Generation *(11)*								
Deterministic jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.14	—	—	0.14	UI
Total jitter (peak-to-peak)	Pattern = CRPAT	—	—	0.279	—	—	0.279	UI

Configuration

Table 1–50 lists the configuration mode specifications for Arria II GX and GZ devices.

Table 1–50. Configuration Mode Specifications for Arria II Devices

Programming Mode	DCLK Frequency			Unit
	Min	Typ	Max	
Passive serial	—	—	125	MHz
Fast passive parallel	—	—	125	MHz
Fast active serial (fast clock)	17	26	40	MHz
Fast active serial (slow clock)	8.5	13	20	MHz
Remote update only in fast AS mode	—	—	10	MHz

JTAG Specifications

Table 1–51 lists the JTAG timing parameters and values for Arria II GX and GZ devices.

Table 1–51. JTAG Timing Parameters and Values for Arria II Devices

Symbol	Description	Min	Max	Unit
t_{JCP}	TCK clock period	30	—	ns
t_{JCH}	TCK clock high time	14	—	ns
t_{JCL}	TCK clock low time	14	—	ns
$t_{JPSU\ (TDI)}$	TDI JTAG port setup time	1	—	ns
$t_{JPSU\ (TMS)}$	TMS JTAG port setup time	3	—	ns
t_{JPH}	JTAG port hold time	5	—	ns
t_{JPCO}	JTAG port clock to output	—	11	ns
t_{JPZX}	JTAG port high impedance to valid output	—	14	ns
t_{JPXZ}	JTAG port valid output to high impedance	—	14	ns

Chip-Wide Reset (Dev_CLRn) Specifications

Table 1–52 lists the specifications for the chip-wide reset (`Dev_CLRn`) for Arria II GX and GZ devices.

Table 1–52. Chip-Wide Reset (Dev_CLRn) Specifications for Arria II Devices

Description	Min	Typ	Max	Unit
`Dev_CLRn`	500	—	—	µs

Table 1–53. High-Speed I/O Specifications for Arria II GX Devices (Part 4 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
f_{HSDR} (data rate)	SERDES factor J = 3 to 10	*(3)*	945 *(7)*	*(3)*	945 *(7)*	*(3)*	740 *(7)*	*(3)*	640 *(7)*	Mbps
	SERDES factor J = 2 (using DDR registers)	*(3)*	*(7)*	*(3)*	*(7)*	*(3)*	*(7)*	*(3)*	*(7)*	Mbps
	SERDES factor J = 1 (using SDR registers)	*(3)*	*(7)*	*(3)*	*(7)*	*(3)*	*(7)*	*(3)*	*(7)*	Mbps
Soft-CDR PPM tolerance	Soft-CDR mode	—	300	—	300	—	300	—	300	±PPM
DPA run length	DPA mode	—	10,000	—	10,000	—	10,000	—	10,000	UI
Sampling window (SW)	Non-DPA mode *(5)*	—	300	—	300	—	350	—	400	ps

Notes to Table 1–53:

(1) $f_{HSCLK\_IN} = f_{HSDR}$ / W. Use W to determine the supported selection of input reference clock frequencies for the desired data rate.

(2) Applicable for interfacing with DPA receivers only. For interfacing with non-DPA receivers, you must calculate the leftover timing margin in the receiver by performing link timing closure analysis. For Arria II GX transmitter to Arria II GX non-DPA receiver, the maximum supported data rate is 945 Mbps. For data rates above 840 Mbps, perform PCB trace compensation by adjusting the PCB trace length for LVDS channels to improve channel-to-channel skews.

(3) The minimum and maximum specification depends on the clock source (for example, PLL and clock pin) and the clock routing resource you use (global, regional, or local). The I/O differential buffer and input register do not have a minimum toggle rate.

(4) The specification is only applicable under the influence of core noise.

(5) Applicable for true LVDS using dedicated SERDES only.

(6) Dedicated SERDES and DPA features are only available on the right banks.

(7) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and the receiver sampling margin to determine the leftover timing margin.

Table 1–54 lists the high-speed I/O timing for Arria II GZ devices.

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices *(Note 1), (2), (10)* (Part 1 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Clock								
f_{HSCLK_in} (input clock frequency) true differential I/O standards	Clock boost factor W = 1 to 40 *(3)*	5	—	717	5	—	717	MHz
f_{HSCLK_in} (input clock frequency) single ended I/O standards *(9)*	Clock boost factor W = 1 to 40 *(3)*	5	—	717	5	—	717	MHz
f_{HSCLK_in} (input clock frequency) single ended I/O standards *(10)*	Clock boost factor W = 1 to 40 *(3)*	5	—	420	5	—	420	MHz

Table 1–54. High-Speed I/O Specifications for Arria II GZ Devices *(Note 1), (2), (10)* (Part 2 of 3)

Symbol	Conditions	C3, I3			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
f_{HSCLK_OUT} (output clock frequency)	—	5	—	717 *(7)*	5	—	717 *(7)*	MHz
Transmitter								
f_{HSDR} (true LVDS output data rate)	SERDES factor, J = 3 to 10 (using dedicated SERDES) *(8)*	*(4)*	—	1250	*(4)*	—	1250	Mbps
	SERDES factor J = 2, (using DDR registers)	*(4)*	—	*(5)*	*(4)*	—	*(5)*	Mbps
	SERDES factor J = 1, (uses an SDR register)	*(4)*	—	*(5)*	*(4)*	—	*(5)*	Mbps
f_{HSDR} (emulated LVDS_E_3R output data rate) *(5)*	SERDES factor J = 4 to 10	*(4)*	—	1152	*(4)*	—	800	Mbps
f_{HSDR} (emulated LVDS_E_1R output data rate)		*(4)*	—	200	*(4)*	—	200	Mbps
$t_{x\ Jitter}$	Total jitter for data rate, 600 Mbps to 1.6 Gbps	—	—	160	—	—	160	ps
	Total jitter for data rate, < 600 Mbps	—	—	0.1	—	—	0.1	UI
$t_{x\ Jitter}$ - emulated differential I/O standards with three external output resistor network	Total jitter for data rate, 600 Mbps to 1.25 Gbps	—	—	300	—	—	325	ps
	Total jitter for data rate < 600 Mbps	—	—	0.2	—	—	0.25	UI
$t_{x\ Jitter}$ - emulated differential I/O standards with one external output resistor network	—	—	—	0.15	—	—	0.15	UI
t_{DUTY}	TX output clock duty cycle for both True and emulated differential I/O standards	45	50	55	45	50	55	%

Table 1–55. DPA Lock Time Specifications for Arria II Devices *(Note 1)*, *(2)*, *(3)*

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions *(4)*	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Notes to Table 1–55:

(1) The DPA lock time is for one channel.

(2) One data transition is defined as a 0-to-1 or 1-to-0 transition.

(3) The DPA lock time stated in the table applies to both commercial and industrial grade.

(4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 1–5 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at a data rate less than 1.25 Gbps and all the Arria II GX devices.

Figure 1–5. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for All Arria II GX Devices and for Arria II GZ Devices at a Data Rate less than 1.25 Gbps

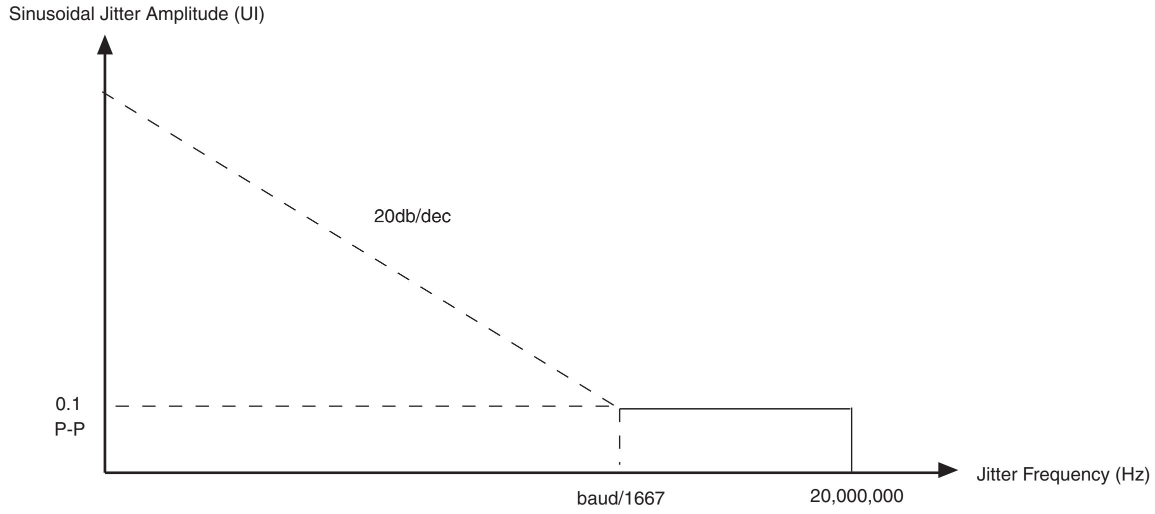


Table 1–57. External Memory Interface Specifications for Arria II GX Devices (Part 2 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode *(1)*	Number of Delay Chains
	C4	I3, C5, I5	C6			
5	270-410	270-380	270-320	36	High	10
6	320-450	320-410	320-370	45	High	8

Note to Table 1–57:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–58 lists the DLL frequency range specifications for Arria II GZ devices.

Table 1–58. DLL Frequency Range Specifications for Arria II GZ Devices

Frequency Mode	Frequency Range (MHz)		Available Phase Shift	DQS Delay Buffer Mode *(1)*	Number of Delay Chains
	–3	–4			
0	90-130	90-120	22.5°, 45°, 67.5°, 90°	Low	16
1	120-170	120-160	30°, 60°, 90°, 120°	Low	12
2	150-210	150-200	36°, 72°, 108°, 144°	Low	10
3	180-260	180-240	45°, 90°,135°, 180°	Low	8
4	240-320	240-290	30°, 60°, 90°, 120°	High	12
5	290-380	290-360	36°, 72°, 108°, 144°	High	10
6	360-450	360-450	45°, 90°, 135°, 180°	High	8
7	470-630	470-590	60°, 120°, 180°, 240°	High	6

Note to Table 1–58:

(1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–59 lists the DQS phase offset delay per stage for Arria II GX devices.

Table 1–59. DQS Phase Offset Delay Per Setting for Arria II GX Devices *(Note 1)*, *(2)*, *(3)*

Speed Grade	Min	Max	Unit
C4	7.0	13.0	ps
I3, C5, I5	7.0	15.0	ps
C6	8.5	18.0	ps

Notes to Table 1–59:

(1) The valid settings for phase offset are -64 to +63 for frequency modes 0 to 3 and -32 to +31 for frequency modes 4 to 5.

(2) The typical value equals the average of the minimum and maximum values.

(3) The delay settings are linear.

Glossary

Table 1–68 lists the glossary for this chapter.

Table 1–68. Glossary (Part 1 of 4)

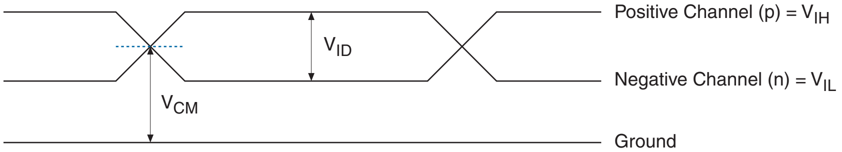
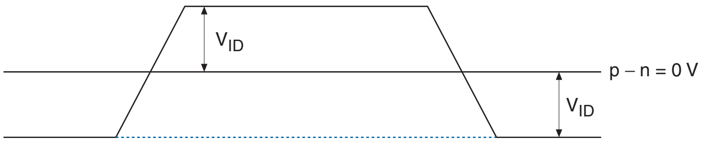
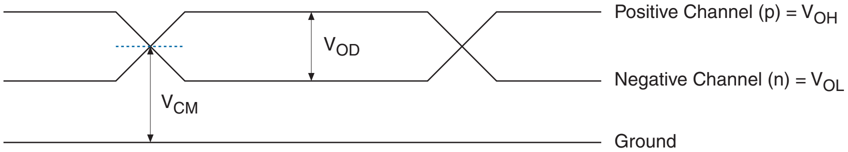
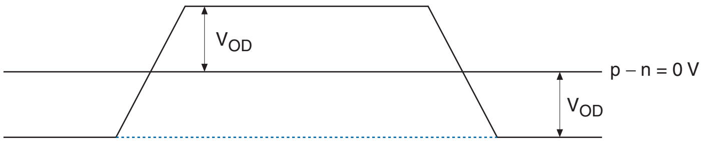
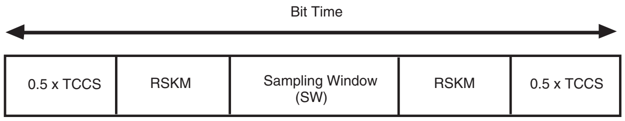
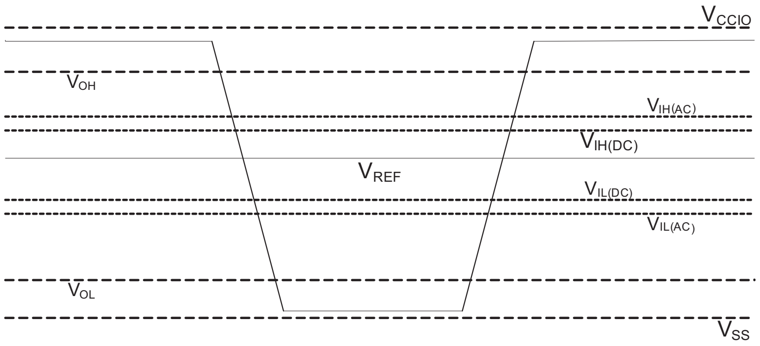
Letter	Subject	Definitions
A, **B,** **C,** **D**	Differential I/O Standards	*Receiver Input Waveforms* **Single-Ended Waveform**  **Differential Waveform**  *Transmitter Output Waveforms* **Single-Ended Waveform**  **Differential Waveform** 
E, **F**	f_{HSCLK}	Left/Right PLL input clock frequency.
	f_{HSDR}	High-speed I/O block: Maximum/minimum LVDS data transfer rate (f_{HSDR} = 1/TUI), non-DPA.
	$f_{HSDRDPA}$	High-speed I/O block: Maximum/minimum LVDS data transfer rate ($f_{HSDRDPA}$ = 1/TUI), DPA.

Table 1–68. Glossary (Part 3 of 4)

Letter	Subject	Definitions
S	**SW (sampling window)**	The period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window: *Timing Diagram* 
	Single-ended Voltage Referenced I/O Standard	The JEDEC standard for SSTL and HSTL I/O standards define both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the AC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: *Single-Ended Voltage Referenced I/O Standard* 
T	t_C	High-speed receiver and transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the *Timing Diagram* figure under **S** in this table).
	t_{DUTY}	High-speed I/O block: Duty cycle on the high-speed transmitter output clock. **Timing Unit Interval (TUI)** The timing budget allowed for skew, propagation delays, and data sampling window. (TUI = 1/(Receiver Input Clock Frequency Multiplication Factor) = t_C/w)
	t_{FALL}	Signal high-to-low transition time (80-20%)
	t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
	t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
	t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
	t_{RISE}	Signal low-to-high transition time (20-80%).